

Special Issue

Micro/Nano Devices and Its Tribology

Message from the Guest Editor

Summary With the development of more sophisticated manufacturing process (e.g., EUV, extreme ultraviolet), the minimum dimensions of electronic device components have reached down to several nm in order to maximize the level of integration and enhance the performance within a limited volume. This Special Issue seeks to showcase research papers, short communications, and review articles that focus on the tribology of microelectronic devices, soft electronics, MEMS, and other microelectronic devices for tribological applications. Of interest are also papers that examine the tribological properties (i.e., friction, wear, surface engineering, and durability, to name a few) of novel materials for microelectronic devices. We look forward to receiving your submissions! Keywords: tribology of microelectronic devices; tribology of soft electronics; tribology of MEMS; microelectronic devices for tribological applications; tribological properties of the materials for microelectronic devices

Guest Editor

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Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

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